CHIPQUIK® RMA591L0SNL250

Datasheet revision 1.0 www.chipquik.com

RMA Solder Paste Sn96.5/Ag3.0/Cu0.5 T4 (250g jar) ROL0

Product Highlights

Printing speeds up to 100mm/sec
Long stencil life
Wide process window
Clear residue
Low voiding
Excellent wetting compatibility on most board finishes
Print grade
Compatible with enclosed print heads
RoHS 3 and REACH compliant

Specifications

Alloy:	Sn96.5/Ag3.0/Cu0.5
Mesh Size:	T4
Micron (µm) Range:	20-38
Flux Type:	Synthetic RMA
Flux Classification:	ROL0
Metal Load:	88.5% Metal by Weight
Melting Point:	217-220°C (423-428°F)
Packaging:	250g jar
Shelf Life:	Refrigerated >6 months, Unrefrigerated >2 months *See notes below:

*Shelf Life Notes: Chip Quik® solder paste is good past its quoted shelf life, regardless of refrigeration. Before use, visually inspect the solder paste to ensure it is not dried out or clumpy, or check stencil release. If stored in a jar, stir the product thoroughly for 2-3 minutes before inspection and use.

Chip Quik® solder paste is manufactured using high quality synthetic flux and precision atomized metal powder. Chip Quik® solder paste is guaranteed for 12 months from date of manufacture, regardless of refrigeration. If you have any issues with our solder paste, please contact Chip Quik® directly for no charge warranty replacement. Please retain original bill of sale, and solder paste in original container as we may request its return for internal R&D testing purposes.

Printer Operation

Print Speed: 25-100mm/sec
Squeegee Pressure: 70-250g/cm of blade
Under Stencil Wipe: Once every 10-25 prints, or as necessary

Stencil Life

>8 hours @ 20-50% RH 22-28°C (72-82°F)
>4 hours @ 50-70% RH 22-28°C (72-82°F)

Stencil Cleaning

Automated stencil cleaning systems for both stencil and misprinted boards. Manual cleaning using isopropyl alcohol (IPA).

Storage and Handling

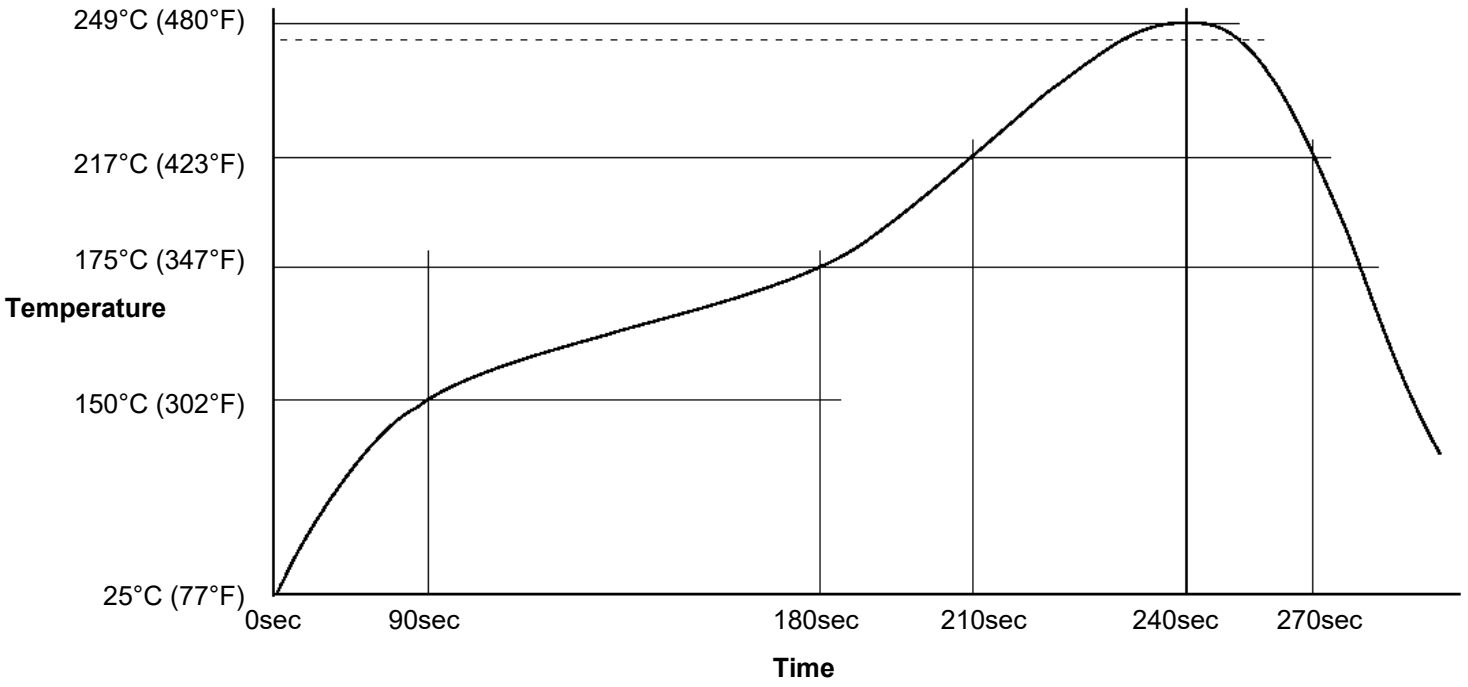
Refrigerate at 3-8°C (37-46°F). Do not freeze. Allow 4 hours for solder paste to reach an operating temperature of 20-25°C (68-77°F) before use.

Transportation

This product has no shipping restrictions. Shipping below 0°C (32°F) or above 25°C (77°F) for normal transit times by ground or air will not impact this product's stated shelf life.

Recommended Profile

Reflow profile for Sn96.5/Ag3.0/Cu0.5 solder assembly, designed as a starting point for process optimization.



Test Results

Test J-STD-004 or other requirements as stated	Test Requirement	Result
Copper Mirror	IPC-TM-650: 2.3.32	M: <50% breakthrough
Corrosion	IPC-TM-650: 2.6.15	M: minor corrosion (uncleaned)
Quantitative Halides	IPC-TM-650: 2.3.28.1	M: ≥0.05 and <0.5%
Electrochemical Migration	IPC-TM-650: 2.6.14.1	M: <1 decade drop (cleaned)
Surface Insulation Resistance 85°C, 85% RH @ 168 Hours	IPC-TM-650: 2.6.3.7	M: ≥100MΩ (cleaned)
Tack Value	IPC-TM-650: 2.4.44	35-40g
Viscosity – Malcom @ 10 RPM/25°C ($x10^3$mPa/s)	IPC-TM-650: 2.4.34.4	Print: 165-225, Dispense: 85-125
Visual	IPC-TM-650: 3.4.2.5	Clear and free from precipitation
Conflict Minerals Compliance	Electronic Industry Citizenship Coalition (EICC)	Compliant
REACH Compliance	Articles 33 and 67 of Regulation (EC) No 1907/2006	Contains no substance >0.1% w/w that is listed as a SVHC or restricted for use in solder materials

Conforms to the following Industry Standards:

J-STD-004B, Amendment 1 (Solder Fluxes):	Yes
J-STD-005A (Solder Pastes):	Yes
J-STD-006C, Amendments 1 & 2 (Solder Alloys and Fluxed/Non-Fluxed Solders):	Yes
RoHS 3 Directive (EU) 2015/863:	Yes

Alloy	Particle Size	Melting Point	Flux Classification	Percent Metal	Packaging	Part Number
Sn63/Pb37	T4 (20-38µm)	183°C (361°F)	ROL0	87.00%	10cc/35g syringe	RMA591AX10
				90.00%	250g jar	RMA591AX250
Sn62/Pb36/Ag2	T4 (20-38µm)	179°C (354°F)	ROL0	87.00%	10cc/35g syringe	RMA591AXS10
				90.00%	250g jar	RMA591AXS250
Sn96.5/Ag3.0/Cu0.5	T4 (20-38µm)	217-220°C (423-428°F)	ROL0	86.00%	10cc/35g syringe	RMA591L0SNL10
				88.50%	250g jar	RMA591L0SNL250
			ROM1	86.00%	10cc/35g syringe	RMA591SNL10
				88.50%	250g jar	RMA591SNL250
Sn42/Bi57.6/Ag0.4	T4 (20-38µm)	138°C (281°F)	ROL0	87.00%	10cc/35g syringe	RMA591L0LT10
				90.00%	250g jar	RMA591L0LT250
			ROM1	87.00%	10cc/35g syringe	RMA591LT10
				90.00%	250g jar	RMA591LT250